Yunhan Chen

List of Publications by Year
in descending order

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18	511	8	13
papers	citations	h-index	g-index
		1163117	1125743

18	18	18	574
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	A Unified Epi-Seal Process for Fabrication of High-Stability Microelectromechanical Devices. Journal of Microelectromechanical Systems, 2016, 25, 489-497.	2.5	107
2	Effective quality factor tuning mechanisms in micromechanical resonators. Applied Physics Reviews, 2018, 5, .	11.3	91
3	Characterization of sensitivity and specificity in leaky droplet-based assays. Lab on A Chip, 2012, 12, 5093.	6.0	67
4	Dynamic modulation of modal coupling in microelectromechanical gyroscopic ring resonators. Nature Communications, 2019, 10, 4980.	12.8	57
5	Environmentally robust differential resonant accelerometer in a wafer-scale encapsulation process. , 2017, , .		51
6	Nonlinearity of Degenerately Doped Bulk-Mode Silicon MEMS Resonators. Journal of Microelectromechanical Systems, 2016, 25, 859-869.	2.5	41
7	Direct Detection of Anchor Damping in MEMS Tuning Fork Resonators. Journal of Microelectromechanical Systems, 2018, 27, 800-809.	2.5	28
8	Quantification of Energy Dissipation Mechanisms in Toroidal Ring Gyroscope. Journal of Microelectromechanical Systems, 2021, 30, 193-202.	2.5	15
9	Thermal-Piezoresistive Tuning of the Effective Quality Factor of a Micromechanical Resonator. Physical Review Applied, 2018, 10, .	3.8	14
10	A unified epi-seal process for resonators and inertial sensors. , 2015, , .		8
11	Robust Method of Fabricating Epitaxially Encapsulated MEMS Devices with Large Gaps. Journal of Microelectromechanical Systems, 2017, 26, 1235-1243.	2.5	8
12	Micro-Tethering for Fabrication of Encapsulated Inertial Sensors With High Sensitivity. Journal of Microelectromechanical Systems, 2019, 28, 372-381.	2.5	7
13	Direct measurements of anchor damping in MEMS resonators. , 2017, , .		6
14	Fabrication of wide and deep cavities for silicon MEMS devices without wafer bonding. , 2017, , .		4
15	Assessing failure in epitaxially encapsulated micro-scale sensors using micro and nano x-ray computed tomography. MRS Communications, 2018, 8, 275-282.	1.8	4
16	Characterization of Accelerated Fatigue in Thick Epi-Polysilicon Vacuum Encapsulated MEMS Resonators. Journal of Microelectromechanical Systems, 2020, 29, 1483-1492.	2.5	2
17	Limits to Thermal-Piezoresistive Cooling in Silicon Micromechanical Resonators. Journal of Microelectromechanical Systems, 2020, 29, 677-684.	2.5	1
18	Influence of Clamping Loss and Electrical Damping On Nonlinear Dissipation in Micromechanical Resonators. , 2022, , .		0